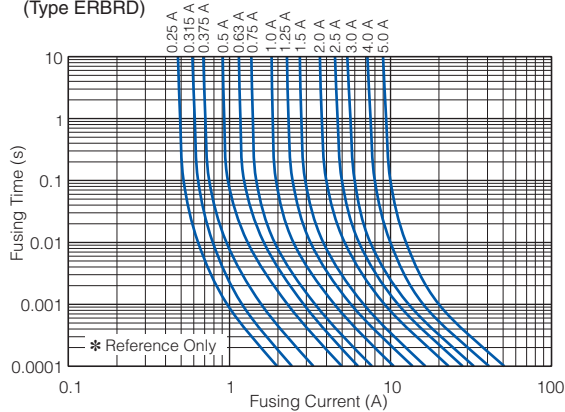
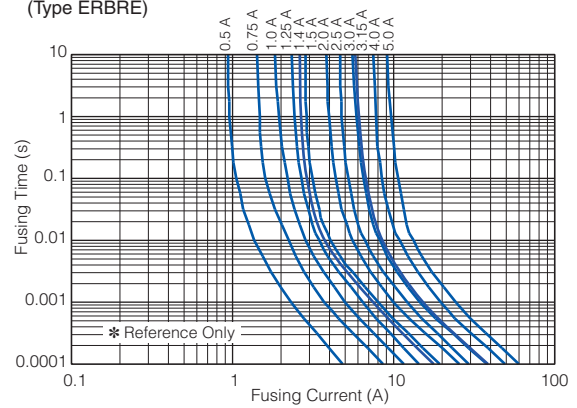


## Fusing Characteristics (25 °C typical)

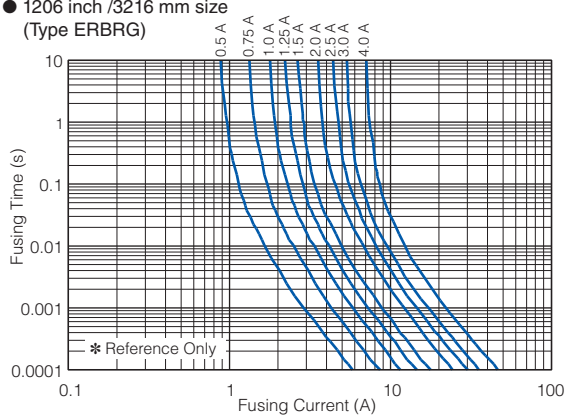
● 0402 inch / 1005 mm size  
(Type ERBRD)



● 0603 inch / 1608 mm size  
(Type ERBRE)



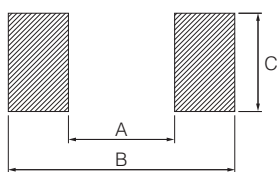
● 1206 inch / 3216 mm size  
(Type ERBRG)



## Performance

Test Item	Performance Requirements	Test Conditions
Resistance	Within Specified Tolerance	25 °C
Resistance to Soldering Heat	±10 %	260 °C±5 °C, 10 s
Rapid Change of Temperature	±10 %	-40 °C (30 min.) / +125 °C (30 min.), 5 cycles
Damp Heat, Steady State	±10 %	60 °C, 90 % to 95 %RH, 1000 h (no load)
Load Life in Humidity	±10 %	60 °C, 90 % to 95 %RH, Load: 70 % rated current, 1000 h
Endurance at 70 °C	±10 %	70 °C, Load: 70 % rated current, 1000 h

## Recommended Soldering Conditions



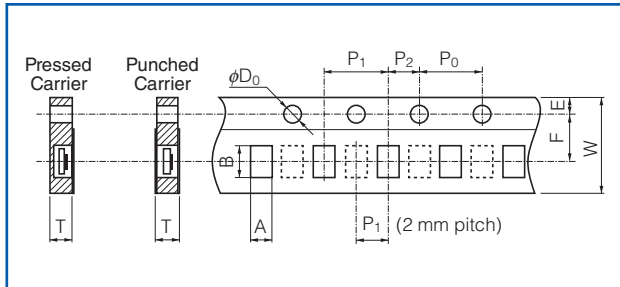
Part No. (inch size)	Dimensions (mm)		
	A	B	C
ERBRD(0402)	0.5 to 0.6	1.4 to 1.6	0.4 to 0.6
ERBRE(0603)	0.7 to 0.9	2.0 to 2.2	0.8 to 1.0
ERBRG(1206)	2.0 to 2.4	4.4 to 5.0	1.2 to 1.8

## Packaging Methods

- Standard Quantity

Part No.	inch size	Kind of Taping	Pitch (P <sub>1</sub> )	Quantity
ERBRD	0402	Pressed Carrier Taping	2 mm	10,000 pcs./ reel
ERBRE	0603	Punched Carrier Taping	4 mm	5,000 pcs./ reel
ERBRG	1206			

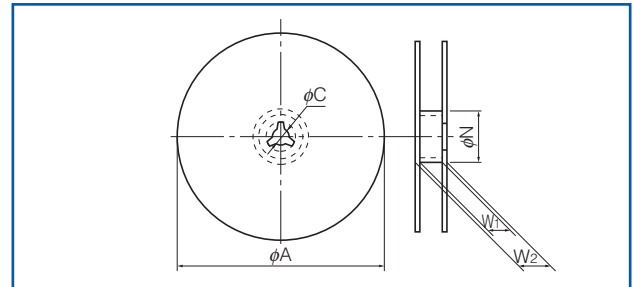
- Carrier Taping (Unit : mm)



Part No.	A	B	W	F	E
ERBRD	0.68 <sup>+0.10</sup>	1.20 <sup>+0.10</sup>	8.00 <sup>+0.20</sup>	3.50 <sup>+0.05</sup>	1.75 <sup>+0.10</sup>
ERBRE	1.10 <sup>+0.10</sup>	1.90 <sup>+0.10</sup>			
ERBRG	2.00 <sup>+0.15</sup>	3.60 <sup>+0.20</sup>			

Part No.	P <sub>1</sub>	P <sub>2</sub>	P <sub>0</sub>	φD <sub>0</sub>	T
ERBRD	2.00 <sup>+0.10</sup>	2.00 <sup>+0.05</sup>	4.00 <sup>+0.10</sup>	1.50 <sup>+0.10</sup>	0.67 <sup>+0.07</sup>
ERBRE	4.00 <sup>+0.10</sup>				0.78 <sup>+0.07</sup>
ERBRG					0.84 <sup>+0.07</sup>

- Taping Reel (Unit : mm)

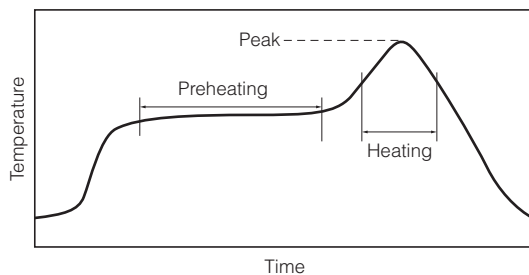


Part No.	φA	φN	φC	W <sub>1</sub>	W <sub>2</sub>
ERBRD ERBRE ERBRG	180.0 <sup>-1.5</sup>	60 <sup>+1.0</sup>	13.0 <sup>+0.2</sup>	9.0 <sup>+1.0</sup>	11.4 <sup>+1.0</sup>

## Recommended Soldering Conditions

Recommendations and precautions are described below.

- Recommended soldering conditions for reflow
  - Reflow soldering shall be performed a maximum of two times.
  - Please contact us for additional information when used in conditions other than those specified.
  - Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



For soldering (Example : Sn/Pb)

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 5 °C	max. 10 s

For lead-free soldering (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

- Recommended soldering conditions for flow

	For soldering		For lead-free soldering	
	Temperature	Time	Temperature	Time
Preheating	140 °C to 180 °C	60 s to 120 s	150 °C to 180 °C	60 s to 120 s
Soldering	245 ± 5 °C	20 s to 30 s	max. 260 °C	max. 10 s

<Repair with hand soldering>

- Preheat with a blast of hot air or similar method. Use a soldering iron with a tip temperature of 350 °C or less. Solder each electrode for 3 seconds or less.
- Never touch this product with the tip of a soldering iron.